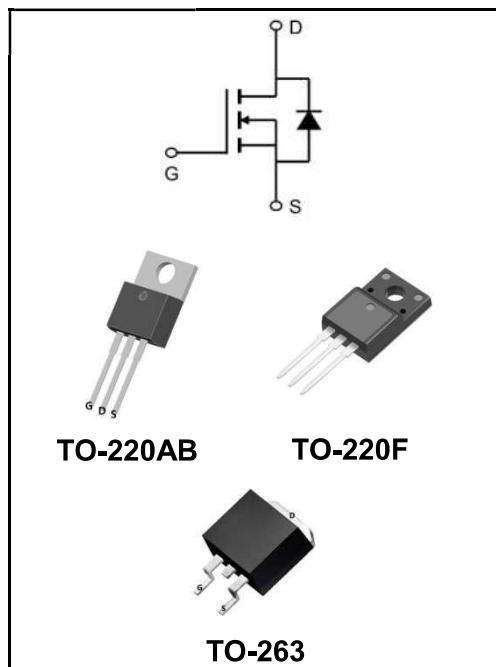


**100V N-CHANNEL ENHANCEMENT MODE MOSFET**
**MAIN CHARACTERISTICS**

$I_D$	80A
$V_{DSS}$	100V
$R_{DS(on)}-typ(@V_{GS}=10V)$	< 9.0mΩ (Type: 7.2mΩ)


**Features**

◆ YFW-SGT technology

**Application**

- ◆ Isolated DC
- ◆ Motor control
- ◆ Synchronous-rectification

**Product Specification Classification**

Part Number	Package	Marking	Pack
YFWG80N10AT	TO-220AB	YFW 80N10AT XXXXX	1000PCS/Box
YFWG80N10AF	TO-220F	YFW 80N10AF XXXXX	1000PCS/Box
YFWG80N10AS	TO-263	YFW 80N10AS XXXXX	800PCS/Reel

**Maximum Ratings at  $T_c=25^\circ\text{C}$  unless otherwise specified**

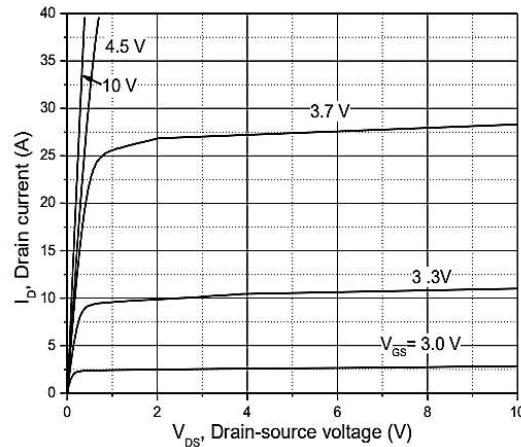
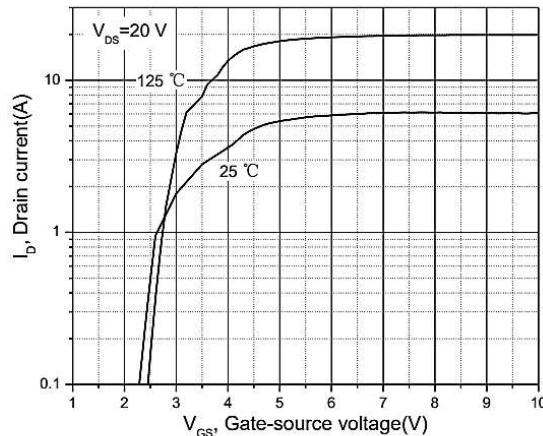
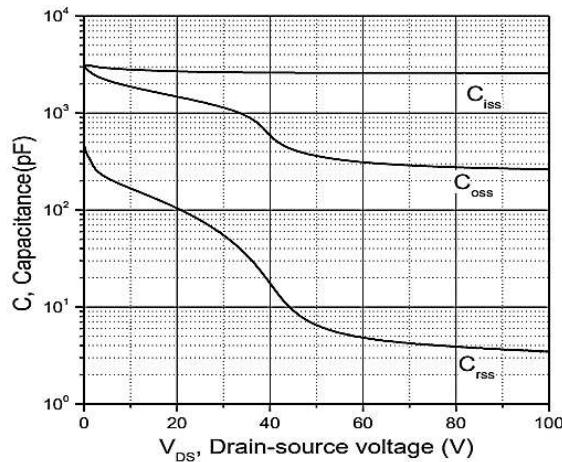
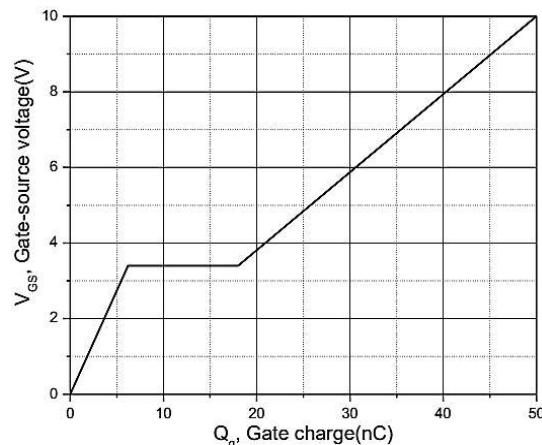
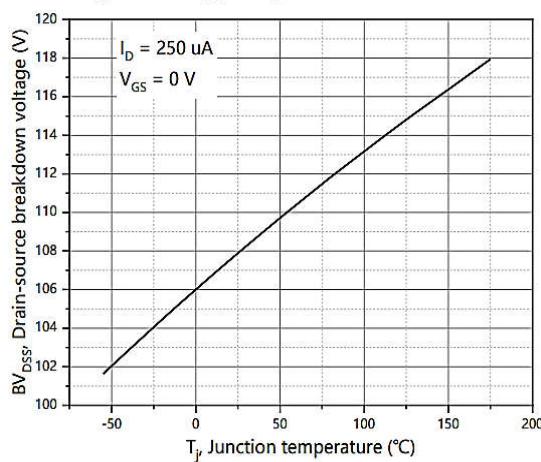
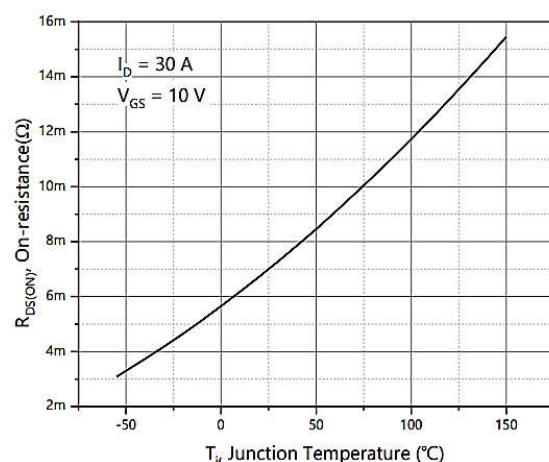
Characteristics	Symbols	Value	Units
Drain-Source Voltage	$V_{DS}$	107	V
Gate - Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>1</sup> @ $T_A=25^\circ\text{C}$	$I_D$	80	A
Continuous Drain Current <sup>1</sup> @ $T_A=70^\circ\text{C}$	$I_D$	62	A
Pulsed drain current <sup>2</sup>	$I_{DM}$	210	A
Single Pulse Avalanche Energy <sup>3</sup>	$E_{AS}$	100	mJ
Avalanche Current	$I_{AS}$	15	A
Total Power dissipation <sup>4</sup> @ $T_A=25^\circ\text{C}$	$P_D$	100	W
Storage Temperature Range	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature Range	$T_J$	-55 to +150	°C
Thermal Resistance Junction-Ambient <sup>1</sup>	$R_{\theta JA}$	62	°C/W
Thermal Resistance, Junction-case <sup>1</sup>	$R_{\theta JC}$	1.25	°C/W

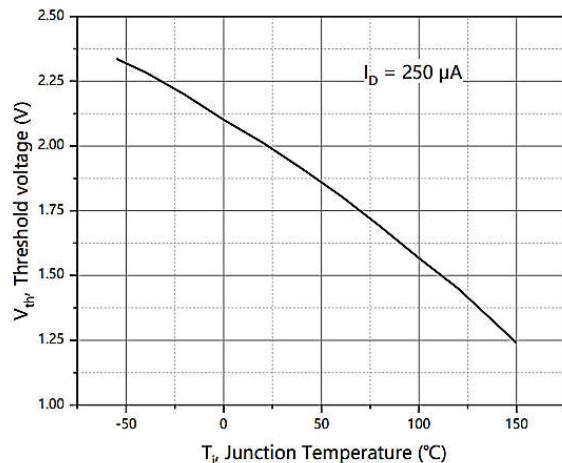
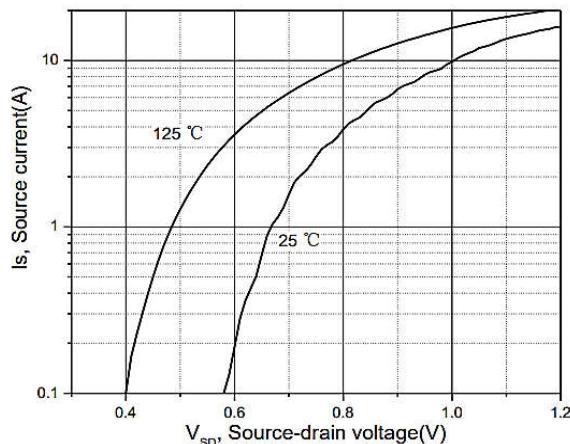
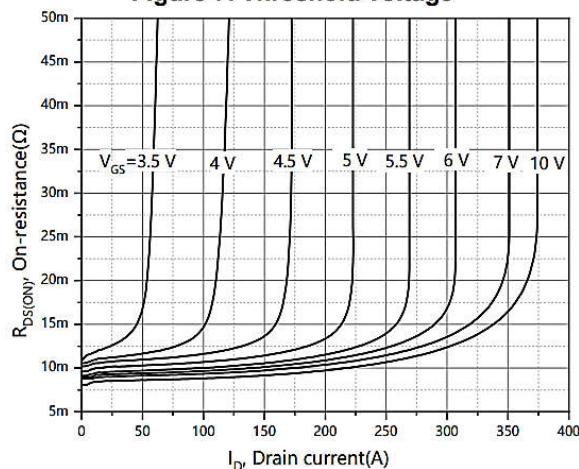
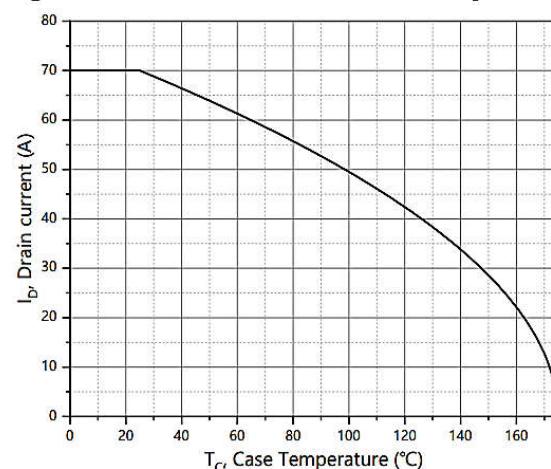
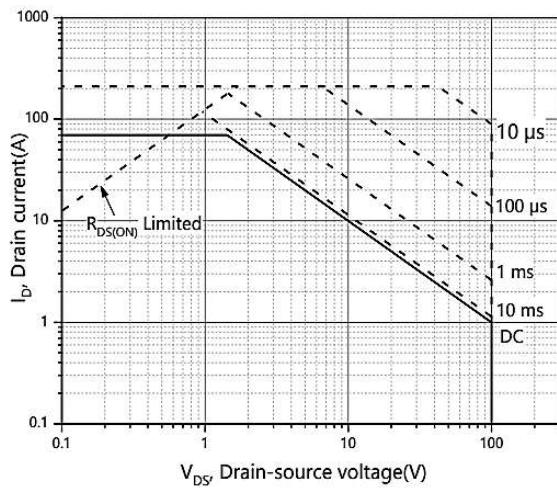
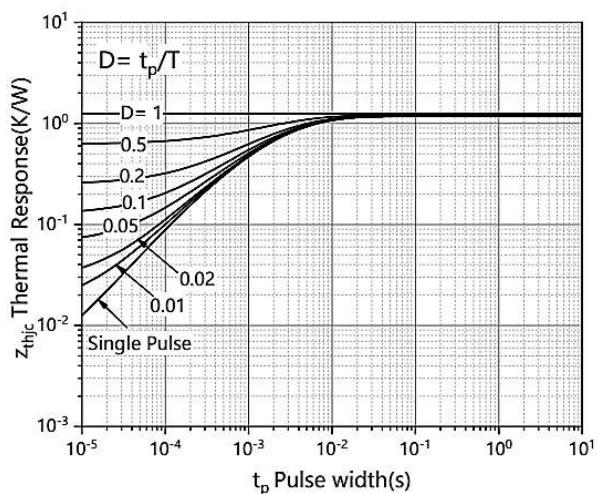
**Maximum Ratings at T<sub>c</sub>=25°C unless otherwise specified**

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	BV <sub>DSS</sub>	107	111	-	V
Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =30A	R <sub>DS(ON)</sub>	-	7.2	9.0	mΩ
	V <sub>GS</sub> =4.5V, I <sub>D</sub> =12A		-	9.0	11	
Gate -Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	V <sub>GS(th)</sub>	1.2	1.8	2.5	V
Drain-Source Leakage Current	V <sub>DS</sub> =100V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	I <sub>DSS</sub>	-	-	1	μA
	V <sub>DS</sub> =100V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C		-	-	5	
Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	I <sub>GSS</sub>	-	-	±100	nA
Total Gate Charge(10V)	V <sub>DS</sub> =50V V <sub>GS</sub> =10V I <sub>D</sub> =25A	Q <sub>g</sub>	-	49.9	-	nC
Total Gate Charge(4.5V)		Q <sub>g</sub>	-	6.5	-	
Gate-Source Charge		Q <sub>gs</sub>	-	12.4	-	
Gate-Drain Charge		Q <sub>gd</sub>	-	3.4	-	
Turn-on delay time	V <sub>DD</sub> =50V V <sub>GS</sub> =10V R <sub>G</sub> =2.2Ω I <sub>D</sub> =25A	t <sub>d(on)</sub>	-	20.6	-	ns
Rise Time		T <sub>r</sub>	-	5	-	
Turn-Off Delay Time		t <sub>d(OFF)</sub>	-	51.8	-	
Fall Time		t <sub>f</sub>	-	9	-	
Input Capacitance	V <sub>DS</sub> =50V V <sub>GS</sub> =0V f=1MHz	C <sub>iss</sub>	-	2640	-	pF
Output Capacitance		C <sub>oss</sub>	-	361	-	
Reverse Transfer Capacitance		C <sub>rss</sub>	-	6.5	-	
Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	I <sub>s</sub>	-	-	5	A
Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>s</sub> =30A , T <sub>J</sub> =25°C	V <sub>SD</sub>	-	-	1.3	V
Reverse Recovery Time	V <sub>r</sub> =50V I <sub>s</sub> =12A, dI/dt=100A/μs , T <sub>J</sub> =25°C	t <sub>rr</sub>	-	60.4	-	ns
Reverse Recovery Charge		Q <sub>rr</sub>	-	106	-	

Note :

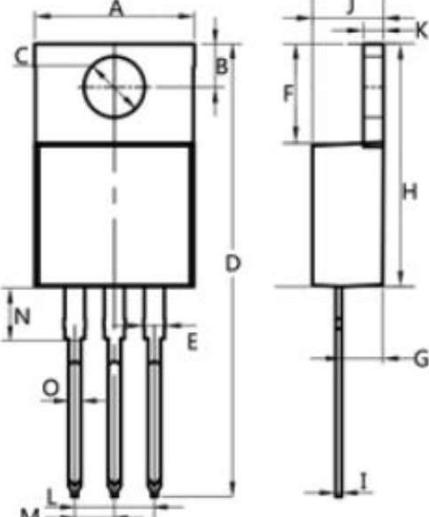
- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3、The EAS data shows Max. rating . The test condition is VDD=30V,VGS=10V, L=0.3 mH, starting Tj=25 °C
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation

**Ratings and Characteristic Curves**
**Typical Characteristics**

**Figure 1. Typ. output characteristics**

**Figure 2. Typ. transfer characteristics**

**Figure 3. Typ. capacitances**

**Figure 4. Typ. gate charge**

**Figure 5. Drain-source breakdown voltage**

**Figure 6. Drain-source on-state resistance**

**Ratings and Characteristic Curves**

**Figure 7. Threshold voltage**

**Figure 8. Forward characteristic of body diode**

**Figure 9. Drain-source on-state resistance**

**Figure 10. Drain current**

**Figure 11. Safe operation area  $T_c=25^\circ\text{C}$** 

**Figure 12. Max. transient thermal impedance**

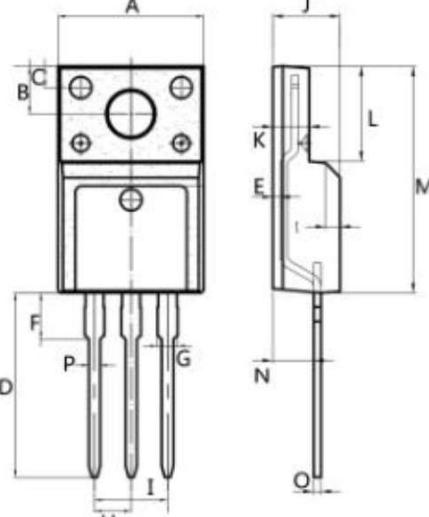
**Package Outline Dimensions Millimeters**

**TO-220AB**



Dim.	Min.	Max.
A	10.15	10.35
B	2.65	2.95
C	3.70	3.90
D	28.5	29.5
E	1.30	1.45
F	6.35	6.55
G	2.9	3.3
H	15.0	16.0
I	0.38	0.42
J	4.45	4.55
K	1.25	1.35
L	Typ 5.08	
M	Typ 2.54	
N	3.1	3.3
O	0.76	0.84
All Dimensions in millimeter		

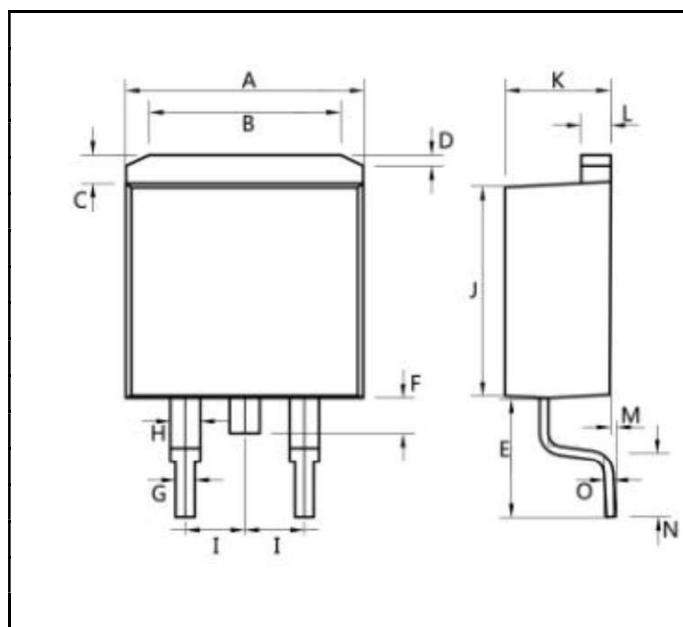
**TO-220F**



Dim.	Min.	Max.
A	9.95	10.25
B	2.95	3.25
C	1.25	1.45
D	12.95	13.25
E	0.50	0.65
F	3.1	3.3
G	1.30	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.60	4.75
K	2.50	2.65
L	6.35	6.55
M	15.4	16.0
N	2.75	3.05
O	0.48	0.52
P	0.76	0.84
All Dimensions in millimeter		

**Package Outline Dimensions Millimeters**

**TO-263**



The technical drawing illustrates the physical dimensions of a TO-263 package. The left view shows the top surface with width A, height C, and lead spacing B. The right view shows the side profile with total height J, lead pitch K, lead thickness L, and lead height M. The bottom view shows the lead configuration with lead width H, lead thickness G, lead spacing I, and lead height O.

Dim.	Min.	Max.
A	10.1	10.2
B	7.4	7.6
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.78	0.86
H	1.2	1.3
I	Typ2.54	
J	8.4	8.6
K	4.45	4.55
L	1.25	1.35
M	0.02	0.1
N	2.4	2.8
O	0.36	0.40

All Dimensions in millimeter